pSemi™
A Murata Company

UltraCMOS®
GREEN

pSEMI MATERIAL DECLARATION FORM

Product:	**PE42542**
Ordering Codes:	**PE42542B-X**
Description:	**UltraCMOS® SP4T RF Switch 9 kHz–18 GHz**
Package:	**29L 4x4 LGA**
Environmental Compliance	EU **RoHS** Directive 2011/65/EC, **REACH** - EU ECHA SVHC, **Arsenic Free**, **JIG 101** - EIA/EICTA/JEITA, **Halogen Free** - IEC61249-2-21, **PFOS Free** - 2006/122/EC, **Antimony Trioxide Free**
Lead Finish	**NiPdAu**
Availability	**Now**

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	1.595258	4.98%	49,802.29
Die	Aluminum	7429-90-5	0.004852	0.02%	151.49
Die	Silicon	7440-21-3	0.000323	0.00%	10.10
Die	Arsenic	7440-38-2	0.000002	0.00%	0.05
Die	Boron	7440-42-8	0.000002	0.00%	0.05
Die	Phosphorus	7723-14-0	0.000006	0.00%	0.20
Die	Titanium	7440-32-6	0.000809	0.00%	25.25
Die	Tungsten	7440-33-7	0.016175	0.05%	504.96
Die	Cobalt	7440-48-4	0.000032	0.00%	1.01
Die	Copper	7440-50-8	0.000013	0.00%	0.40
Solder Bump	Tin	7440-31-5	0.065807	0.21%	2,054.42
Solder Bump	Silver	7440-22-4	0.002412	0.01%	75.29
Solder Bump	Copper	7440-50-8	0.000689	0.00%	21.51
Solder Bump	Benzocyclobutene	694-87-1	0.000007	0.00%	0.21
UBM	Aluminum	7429-90-5	0.000149	0.00%	4.65
UBM	Nickel	7440-02-0	0.000012	0.00%	0.36
UBM	Vanadium	7440-62-2	0.000158	0.00%	4.92
UBM	Copper	7440-50-8	0.000411	0.00%	12.84
Substrate	Bismaleimide	105391-33-1	0.019700	0.06%	615.01
Substrate	Triazine resin	25722-66-1	0.019700	0.06%	615.01
Substrate	Epoxy resin	9003-36-5	0.019700	0.06%	615.01
Substrate	Inorganic Filler	21645-51-2	0.039300	0.12%	1,226.91
Substrate	Continuous Filament Fiber Glass	65997-17-3	0.039300	0.12%	1,226.91
Substrate	Copper	7440-50-8	0.059000	0.18%	1,841.92
Substrate	Nickel	7440-02-0	0.013600	0.04%	424.58
Substrate	Palladium	7440-05-3	0.000800	0.00%	24.98
Substrate	Gold	7440-57-5	0.000800	0.00%	24.98
Molding Compound	Solid Epoxy Resin	Proprietary	3.013300	9.41%	94,072.09
Molding Compound	Phenol Resin	Proprietary	2.109300	6.59%	65,850.15
Molding Compound	Carbon Black	1333-86-4	0.301300	0.94%	9,406.27
Molding Compound	Metal Hydroxide	Proprietary	0.904000	2.82%	28,221.94
Molding Compound	Amorphous silica	60676-86-0	22.900900	71.49%	714,942.29
Molding Compound	Crystalline silica	14808-60-7	0.904000	2.82%	28,221.94
Total Weight (mg)			**32.031816**	100.00%	1,000,000